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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/766,623	01/23/2001	Wen-Ching Chen	MR1683-291 8367	
75	90 05/29/2003			
ROSENBERG, KLEIN & LEE SUITE 101 3458 ELLICOTT CENTER DRIVE			EXAMINER	
			WORKU, NEGUSSIE	
ELLICOTT CI.	ΓY, MD 21043		ART UNIT PAPER NUMBER	
			2624	j.
			DATE MAILED: 05/29/2003	4

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)			
Office Action Summary		•				
		09/766,623	CHEN, WEN-CHING			
		Examiner	Art Unit			
	The MAILING DATE of this communication app	Negussie Worku ears on the cover sheet with the cover	2624 correspondence address			
Period for Reply						
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.  - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.  - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).  - Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).  Status						
1)⊠	Responsive to communication(s) filed on 26 h	<u>//arch 2003</u> .				
2a)⊠	This action is <b>FINAL</b> . 2b) ☐ Thi	is action is non-final.				
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims						
4)⊠ Claim(s) <u>6-12</u> is/are pending in the application.						
	4a) Of the above claim(s) is/are withdrawn from consideration.					
5)	Claim(s) is/are allowed.					
6)⊠	6)⊠ Claim(s) <u>6-12</u> is/are rejected.					
7)	Claim(s) is/are objected to.					
8) Claim(s) are subject to restriction and/or election requirement.  Application Papers						
9) The specification is objected to by the Examiner.						
10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.						
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
11) The proposed drawing correction filed on is: a) ☐ approved b) ☐ disapproved by the Examiner.						
If approved, corrected drawings are required in reply to this Office action.						
12) The oath or declaration is objected to by the Examiner.						
Priority under 35 U.S.C. §§ 119 and 120						
13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).						
a) ☐ All b) ☐ Some * c) ☐ None of:						
	1. Certified copies of the priority documents have been received.					
	2. Certified copies of the priority documents have been received in Application No					
<ul> <li>3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).</li> <li>* See the attached detailed Office action for a list of the certified copies not received.</li> </ul>						
14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).						
a) ☐ The translation of the foreign language provisional application has been received. 15)☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.						
Attachment(s)  1) St Notice of References Cited (DTO 803)  (DTO 412) Report Note:  (DTO 412) Report No						
1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413) Paper No(s) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 5) Notice of Informal Patent Application (PTO-152) 6) Other:						

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## **DETAILED ACTION**

- 1. Applicant's response filed March 26, 2003, with respect to claims 6-12 have been considered but are most in view of the new ground(s) of rejection and this office action is final.
- 2. The title of the invention is not descriptive. A new title is required that is clearly indicative of the invention to which the claims are directed the following title is suggested: "Image pickup module"

## Claim Rejections - 35 USC § 102

- 3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:
  - (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section  $371 \odot$  of this title before the invention thereof by the applicant for patent.
- 4. Claims 6-12, are rejected under 35 U.S.C. 102(e) as being anticipated by Yoon (USP 6066090).

With respect to claim 6, Yoon discloses an image pickup module (image receiver 56b is a solid-state image sensor 250, as shown in fig 10, see col.4, lines 13-15) comprising: a circuit main board (circuit board or a substrate 250c of fig 10); an image sensor (image sensor chip 250e

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of fig 10, col.8, lines 56-58), coupled to said circuit board, (image sensor 250e coupled to circuit board or a substrate 250c of fig 10), said image sensor (image sensor 250 of fig 10), including a coupling transistor device (planer chips 250e of fig 10), disposed within a housing package (housing 46 of fig 10) having a peripheral portion, see (col.8, lines 57-58); a lens (lens 250b of fig 10, see col.54-55) seat being disposed on said image sensor (image sensor 250 of fig 10, see col.8, lines 43-45), said lens seat including a connection section (substrate 250c of fig 10, carry electrical connection, see col.8, lines 55-58), and image pickup cylinder section (image sensor housing 46 of fig 10, has a cylindrical shape), extending therefrom, said connecting section (250c of fig 10) and an image pickup cylinder section extending therefrom, said connecting section (250c of fig 10) engaging said peripheral portion of said image sensor (250 of fig 10) housing package to be guided there by into an aline position (250i an axis of lens aline position); and a lens (250b of fig 10) coupled to said image pickup cylinder section (housing 46 of fig 10) of said lens seat, said lens having an axis (250i of fig 10) aligned in predetermined manner relative to said coupling transistor device ((planer chips 250e of fig 10), when said connecting section (250c (substrate or board as a connection means 250c of fig 10, see col.8, lines 55-58) of said lens (lens element 250b of fig 10) seat is disposed in said aligned position (aline with axis 250i of fig 10).

With respect to claim 7, Yoon discloses the image pickup module (250 of fig 10), wherein said lens (250b of fig 10) seat extend over and peripherally envelops a top of said image sensor (250e of fig 10).

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With respect to claim 8, Yoon discloses the image pickup module (250 of fig 10), wherein said connecting section (250d of fig 10) has formed thereon first and second faces defining an inner flange portion to retentively engaged said peripheral portion of said image sensor housing package (46 as a housing, optical package 250a of fig 10, see col.8, lines 53-55).

With respect to claim 9, Yoon discloses the image pickup module (250 of fig 10, see col.8, lines 42-44), further comprising a sealing glass sheet overlaying a least a portion of said image sensor housing package.

With respect to claim 10, Yoon discloses a CCD image pickup module (as shown in fig 2, see col.4, lines 22-24), wherein said sealing glass sheet (250h of fig 10, see col.9, lines 31-35) is disposed in peripherally flush manner over said image sensor (250 of fig 10) housing package.

With respect to claim 11, Yoon discloses the image pickup module (250 of fig 10, wherein said sealing glass sheet (250h of fig 10) is less in peripheral extent than said image sensor housing package (image sensor 250 of fig 10, housing 46 of fig 10).

With respect to claim 12, Yoon discloses the image pickup module (250 of fig 10, see col.8, lines 443-45), further comprising a sealing glass sheet (250h of fig 10) overlaying a least a portion of said image sensor (25 of fig 10) housing package, said peripheral portion of said image

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sensor housing package extending peripherally beyond said sealing glass sheet, see (col.8, lines

33-36).

3. Any inquiry concerning this communication or earlier communication from Examiner

should be directed to Negus Worku whose telephone number is (703) 305 5441.

The Examiner can normally be reached on M-F, 9 am - 6 pm if attempts to reach the

Examiner by telephone are unsuccessful, the Examiner's Supervisor, David Moore, can be

reached on (703) 308-7452.

The fax phone number for the organization where this application or proceeding is

assigned is (703) 306-5406, and any inquiry of general nature or relating to the status of this

application or proceeding should be directed to the receptionist whose telephone number is (703)

305-3900.

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